

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Prior Application: S. IMASU et al
 Serial No. 09/048,054
 Filed: March 26, 1998

3/13
 3/6/01
 M. Frager

Group Art Unit: 2841
 Examiner: J. Vigushin
 For: PROCESS FOR MOUNTING ELECTRONIC
 DEVICE AND SEMICONDUCTOR DEVICE

PRELIMINARY AMENDMENT

Assistant Commissioner of Patents
 Washington, D.C. 20231

Sir:

Prior to examination on the merits, please amend the
 above-identified application as follows:

IN THE SPECIFICATION:

~~Page 7, line 18, after "board)" insert --of the bump
 electrodes--.~~

~~Page 8, line 2, change "Fig. 4 is sections" to -Figs.~~

~~4 (A), 4 (B) and 4 (C) are sectional views--.~~

~~Page 8, line 2, change "Fig. 4 is sections" to
 --Figs. 4 (A), 4 (B) and 4 (C) are sectional views--;~~

~~line 25, change "B - B" to --II - II--.~~

~~Page 9, line 2, change "C - C" to --III - III--;~~

~~line 22, change "A - A" to --I - I--.~~

~~Page 22, line 18, after "(a section)." insert~~

~~--In this case also, as shown in Fig. 11, the passivation film~~

~~5 is not formed between the semiconductor chip 10 and the soft
 layer 3.--~~

TO GET PCT TREATMENT
FILE A PCT
APPLICATION

B1

B2